

## Technical details– MetalClad / IMS – Standard

Parameter	Technical descriptions	Remarks
<b>Basic material</b>	aluminium, copper, steel	different thicknesses depending on requirements
<b>Dielectric</b>	75 - 300 µm	selectable by thermal conductivity
<b>Board thickness</b>	0,3 mm – 4,0 mm	
<b>Copper</b>	35 -210 µm	
<b>Maximum size of circuit boards</b>	600 mm x 1500 mm	
<b>Minimum size of drilling diameter</b>	0,20 mm	Diameter larger than 6mm to be milled.
<b>Line/Space</b>	150 µm / 150 µm	
<b>Thermal conductivity</b>	1,0 - 400 W/mK	according to dielectric and construction
<b>Thermal resistance</b>	0,052 - 0,086 °C/W	TO-220 Test
<b>Dielectric breakdown voltage</b>	30kV/mm	IPC-TM-650 2.5.7
<b>Maximum operating temp.</b>	125°C	UL-746
<b>Tg</b>	130°C	DSC-Test
<b>Dielectric constant (1MHz)</b>	5,4	ASTM D150
<b>Soldering limits</b>	288 °C, 30 sec.	UL
<b>Inflammableness</b>	V-0	UL-94
<b>Customer-specific Requirements</b>	on request	

Stand: December 2015